## **SKKE 120F**



SEMIPACK<sup>®</sup> 2

**Fast Diode Modules** 

**SKKE 120F** 

Fe	eati	ure	S
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- CAL (controlled axial lifetime) chip technology, patent No. DE 43 10 44
- Heat transfer through ceramic isolated metal baseplate
- Very short recovery times
- Soft recovery
- Low switching losses
- UL recognized, file no. E 63 532

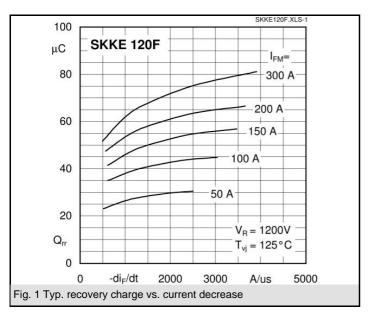
## **Typical Applications**

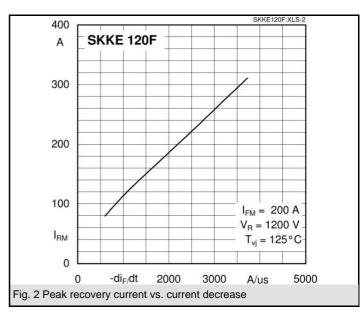
- Self-commutated inverters
- DC choppers
- AC motor speed control
- inductive heating
- Uninterruptible power supplies
- · Electronic welders
- General power switching applications
- snubber and free wheeling circuits

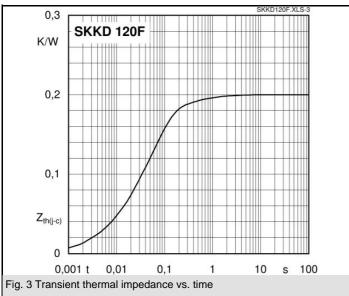
$V_{RSM}$	$V_{RRM}$	I <sub>FRMS</sub> = 220 A (maximum value for continuous operation)		
V	V	$I_{FAV}$ = 120 A (sin. 180, 50 Hz; $T_c$ = 82 °C)		
1700	1700	SKKE 120F17		

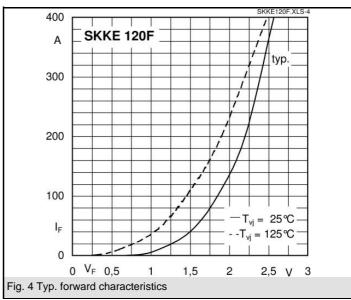
Symbol	Conditions	Values	Units
I <sub>FAV</sub>	sin. 180; T <sub>c</sub> = 85 (100) °C	116 (87)	Α
I <sub>FSM</sub>	T <sub>vi</sub> = 25 °C; 10 ms	2000	Α
	T <sub>vi</sub> = 150 °C; 10 ms	1800	Α
i²t	T <sub>vj</sub> = 25 °C; 8,3 10 ms	20000	A²s
	T <sub>vj</sub> = 150 °C; 8,3 10 ms	16200	A²s
V <sub>F</sub>	T <sub>vi</sub> = 25 °C; I <sub>F</sub> = 200 A	max. 2,7	V
$V_{(TO)}$	T <sub>vj</sub> = 150 °C	max. 1,5	V
$r_T$	T <sub>vj</sub> = 150 °C	max. 4,5	mΩ
I <sub>RD</sub>	$T_{vj} = 25 \text{ °C}; V_{RD} = V_{RRM}$	max. 0,4	mA
$I_{RD}$	$T_{vj}$ = 125 °C; $V_{RD}$ = $V_{RRM}$	max. 50	mA
Q <sub>rr</sub>	T <sub>vj</sub> = 125 °C, I <sub>F</sub> = 120 A,	41	μC
I <sub>RM</sub>	$-di/dt = 1000 \text{ A/}\mu\text{s}, V_R = 1200 \text{ V}$	110	Α
t <sub>rr</sub>		1020	ns
E <sub>rr</sub>		10	mJ
R <sub>th(j-c)</sub>		0,2	K/W
R <sub>th(c-s)</sub>		0,05	K/W
$T_{vj}$		- 40 <b>+</b> 150	°C
T <sub>stg</sub>		- 40 + 125	°C
V <sub>isol</sub>	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	4800 / 4000	V~
$M_s$	to heatsink	5 ± 15 %	Nm
$M_t$	to terminals	5 ± 15 %	Nm
а		5 * 9,81	m/s²
m	approx.	160	g
Case		A 54	

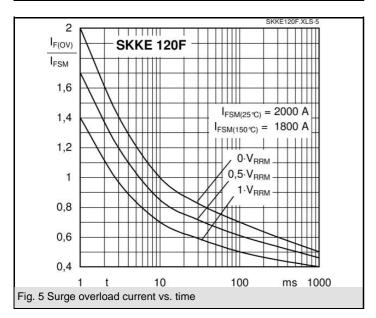




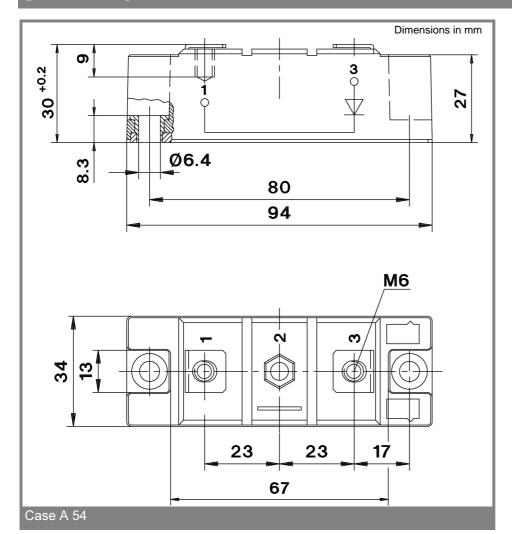


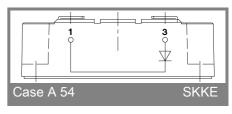






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